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Details

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Product Status	Active
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	·
Peripherals	LVD, POR, PWM
Number of I/O	5
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	·
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.209", 5.30mm Width)
Supplier Device Package	8-50
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mchc908qt4mdwe

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General Description



Memory

- 8. Wait for time, t_{PROG} (minimum 30 μ s).
- 9. Repeat step 7 and 8 until all desired bytes within the row are programmed.
- 10. Clear the PGM $bit^{(1)}$.
- 11. Wait for time, t_{NVH} (minimum 5 μ s).
- 12. Clear the HVEN bit.
- 13. After time, t_{RCV} (typical 1 μ s), the memory can be accessed in read mode again.

NOTE

The COP register at location \$FFFF should not be written between steps 5–12, when the HVEN bit is set. Since this register is located at a valid FLASH address, unpredictable behavior may occur if this location is written while HVEN is set.

This program sequence is repeated throughout the memory until all data is programmed.

NOTE

Programming and erasing of FLASH locations cannot be performed by code being executed from the FLASH memory. While these operations must be performed in the order shown, other unrelated operations may occur between the steps. Do not exceed t_{PROG} maximum, see 16.16 Memory Characteristics.

2.6.5 FLASH Protection

Due to the ability of the on-board charge pump to erase and program the FLASH memory in the target application, provision is made to protect blocks of memory from unintentional erase or program operations due to system malfunction. This protection is done by use of a FLASH block protect register (FLBPR). The FLBPR determines the range of the FLASH memory which is to be protected. The range of the protected area starts from a location defined by FLBPR and ends to the bottom of the FLASH memory (\$FFFF). When the memory is protected, the HVEN bit cannot be set in either ERASE or PROGRAM operations.

NOTE

In performing a program or erase operation, the FLASH block protect register must be read after setting the PGM or ERASE bit and before asserting the HVEN bit.

When the FLBPR is programmed with all 0 s, the entire memory is protected from being programmed and erased. When all the bits are erased (all 1's), the entire memory is accessible for program and erase.

When bits within the FLBPR are programmed, they lock a block of memory. The address ranges are shown in 2.6.6 FLASH Block Protect Register. Once the FLBPR is programmed with a value other than FF, any erase or program of the FLBPR or the protected block of FLASH memory is prohibited. Mass erase is disabled whenever any block is protected (FLBPR does not equal FF). The FLBPR itself can be erased or programmed only with an external voltage, V_{TST} , present on the IRQ pin. This voltage also allows entry from reset into the monitor mode.

^{2.} The time between each FLASH address change, or the time between the last FLASH address programmed to clearing PGM bit, must not exceed the maximum programming time, t_{PROG} maximum.



FLASH Memory (FLASH)





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Chapter 3 Analog-to-Digital Converter (ADC)

3.1 Introduction

This section describes the analog-to-digital converter (ADC). The ADC is an 8-bit, 4-channel analog-todigital converter. The ADC module is only available on the MC68HC908QY2, MC68HC908QT2, MC68HC908QY4, and MC68HC908QT4.

3.2 Features

Features of the ADC module include:

- 4 channels with multiplexed input
- · Linear successive approximation with monotonicity
- 8-bit resolution
- Single or continuous conversion
- Conversion complete flag or conversion complete interrupt
- Selectable ADC clock frequency

3.3 Functional Description

Four ADC channels are available for sampling external sources at pins PTA0, PTA1, PTA4, and PTA5. An analog multiplexer allows the single ADC converter to select one of the four ADC channels as an ADC voltage input (ADCVIN). ADCVIN is converted by the successive approximation register-based counters. The ADC resolution is eight bits. When the conversion is completed, ADC puts the result in the ADC data register and sets a flag or generates an interrupt.

Figure 3-2 shows a block diagram of the ADC.

3.3.1 ADC Port I/O Pins

PTA0, PTA1, PTA4, and PTA5 are general-purpose I/O pins that are shared with the ADC channels. The channel select bits (ADC status and control register (ADSCR), \$003C), define which ADC channel/port pin will be used as the input signal. The ADC overrides the port I/O logic by forcing that pin as input to the ADC. The remaining ADC channels/port pins are controlled by the port I/O logic and can be used as general-purpose I/O. Writes to the port register or data direction register (DDR) will not have any affect on the port pin that is selected by the ADC. Read of a port pin which is in use by the ADC will return a 0 if the corresponding DDR bit is at 0. If the DDR bit is at 1, the value in the port data latch is read.



Analog-to-Digital Converter (ADC)

3.3.2 Voltage Conversion

When the input voltage to the ADC equals V_{DD} , the ADC converts the signal to \$FF (full scale). If the input voltage equals V_{SS} , the ADC converts it to \$00. Input voltages between V_{DD} and V_{SS} are a straight-line linear conversion. All other input voltages will result in \$FF if greater than V_{DD} and \$00 if less than V_{SS} .

NOTE

Input voltage should not exceed the analog supply voltages.

3.3.3 Conversion Time

Sixteen ADC internal clocks are required to perform one conversion. The ADC starts a conversion on the first rising edge of the ADC internal clock immediately following a write to the ADSCR. If the ADC internal clock is selected to run at 1 MHz, then one conversion will take 16 μ s to complete. With a 1-MHz ADC internal clock the maximum sample rate is 62.5 kHz.

Conversion Time = $\frac{16 \text{ ADC Clock Cycles}}{\text{ADC Clock Frequency}}$

Number of Bus Cycles = Conversion Time \times Bus Frequency

3.3.4 Continuous Conversion

In the continuous conversion mode (ADCO = 1), the ADC continuously converts the selected channel filling the ADC data register (ADR) with new data after each conversion. Data from the previous conversion will be overwritten whether that data has been read or not. Conversions will continue until the ADCO bit is cleared. The COCO bit (ADSCR, \$003C) is set after each conversion and will stay set until the next read of the ADC data register.

When a conversion is in process and the ADSCR is written, the current conversion data should be discarded to prevent an incorrect reading.

3.3.5 Accuracy and Precision

The conversion process is monotonic and has no missing codes.

3.4 Interrupts

When the AIEN bit is set, the ADC module is capable of generating a central processor unit (CPU) interrupt after each ADC conversion. A CPU interrupt is generated if the COCO bit is at 0. The COCO bit is not used as a conversion complete flag when interrupts are enabled.

3.5 Low-Power Modes

The following subsections describe the ADC in low-power modes.

3.5.1 Wait Mode

The ADC continues normal operation during wait mode. Any enabled CPU interrupt request from the ADC can bring the microcontroller unit (MCU) out of wait mode. If the ADC is not required to bring the MCU out of wait mode, power down the ADC by setting the CH[4:0] bits in ADSCR to 1s before executing the WAIT instruction.



3.7.2 ADC Data Register

One 8-bit result register is provided. This register is updated each time an ADC conversion completes.



Figure 3-4. ADC Data Register (ADR)

3.7.3 ADC Input Clock Register

This register selects the clock frequency for the ADC.



Figure 3-5. ADC Input Clock Register (ADICLK)

ADIV2–ADIV0 — ADC Clock Prescaler Bits

ADIV2, ADIV1, and ADIV0 form a 3-bit field which selects the divide ratio used by the ADC to generate the internal ADC clock. Table 3-2 shows the available clock configurations. The ADC clock frequency should be set between $f_{ADIC(MIN)}$ and $f_{ADIC(MAX)}$. The analog input level should remain stable for the entire conversion time (maximum = 17 ADC clock cycles).

ADIV2	ADIV1	ADIV0	ADC Clock Rate
0	0	0	Bus clock ÷ 1
0	0	1	Bus clock ÷ 2
0	1	0	Bus clock ÷ 4
0	1	1	Bus clock ÷ 8
1	Х	Х	Bus clock ÷ 16

Table 3-2. ADC Clock Divide Ratio

X = don't care



Analog-to-Digital Converter (ADC)



Configuration Register (CONFIG)





6.3.7 COPRS (COP Rate Select)

The COPRS signal reflects the state of the COP rate select bit (COPRS) in the configuration register 1 (CONFIG1). See Chapter 5 Configuration Register (CONFIG).

6.4 COP Control Register

The COP control register (COPCTL) is located at address \$FFFF and overlaps the reset vector. Writing any value to \$FFFF clears the COP counter and starts a new timeout period. Reading location \$FFFF returns the low byte of the reset vector.



Figure 6-2. COP Control Register (COPCTL)

6.5 Interrupts

The COP does not generate CPU interrupt requests.

6.6 Monitor Mode

The COP is disabled in monitor mode when V_{TST} is present on the IRQ pin.

6.7 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

6.7.1 Wait Mode

The COP continues to operate during wait mode. To prevent a COP reset during wait mode, periodically clear the COP counter.

6.7.2 Stop Mode

Stop mode turns off the BUSCLKX4 input to the COP and clears the SIM counter. Service the COP immediately before entering or after exiting stop mode to ensure a full COP timeout period after entering or exiting stop mode.

6.8 COP Module During Break Mode

The COP is disabled during a break interrupt with monitor mode when BDCOP bit is set in break auxiliary register (BRKAR).

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Table 7-2. Opcode Map

	Bit Manipulation Branch Read-Modify-Write Control Register/Memory																		
	DIR	DIR	REL	DIR	INH	INH	IX1	SP1	IX	INH	INH	IMM	DIR	EXT	IX2	SP2	IX1	SP1	IX
MSB LSB	0	1	2	3	4	5	6	9E6	7	8	9	Α	В	С	D	9ED	Е	9EE	F
0	5 BRSET0 3 DIR	4 BSET0 2 DIR	3 BRA 2 REL	4 NEG 2 DIR	1 NEGA 1 INH	1 NEGX 1 INH	4 NEG 2 IX1	5 NEG 3 SP1	3 NEG 1 IX	7 RTI 1 INH	BGE 2 REL	2 SUB 2 IMM	3 SUB 2 DIR	4 SUB 3 EXT	4 SUB 3 IX2	5 SUB 4 SP2	3 SUB 2 IX1	4 SUB 3 SP1	2 SUB 1 IX
1	5 BRCLR0 3 DIR	4 BCLR0 2 DIR	3 BRN 2 REL	5 CBEQ 3 DIR	4 CBEQA 3 IMM	4 CBEQX 3 IMM	5 CBEQ 3 IX1+	6 CBEQ 4 SP1	4 CBEQ 2 IX+	4 RTS 1 INH	3 BLT 2 REL	2 CMP 2 IMM	3 CMP 2 DIR	4 CMP 3 EXT	4 CMP 3 IX2	5 CMP 4 SP2	3 CMP 2 IX1	4 CMP 3 SP1	2 CMP 1 IX
2	5 BRSET1 3 DIR	4 BSET1 2 DIR	3 BHI 2 REL		5 MUL 1 INH	7 DIV 1 INH	3 NSA 1 INH		2 DAA 1 INH		3 BGT 2 REL	2 SBC 2 IMM	3 SBC 2 DIR	4 SBC 3 EXT	4 SBC 3 IX2	5 SBC 4 SP2	3 SBC 2 IX1	4 SBC 3 SP1	2 SBC 1 IX
3	5 BRCLR1 3 DIR	4 BCLR1 2 DIR	3 BLS 2 REL	COM 2 DIR	1 COMA 1 INH	COMX 1 INH	4 COM 2 IX1	5 COM 3 SP1	COM 1 IX	9 SWI 1 INH	3 BLE 2 REL	CPX 2 IMM	CPX 2 DIR	4 CPX 3 EXT	4 CPX 3 IX2	5 CPX 4 SP2	3 CPX 2 IX1	4 CPX 3 SP1	CPX 1 IX
4	5 BRSET2 3 DIR	4 BSET2 2 DIR	3 BCC 2 REL	4 LSR 2 DIR	1 LSRA 1 INH	1 LSRX 1 INH	4 LSR 2 IX1	5 LSR 3 SP1	3 LSR 1 IX	2 TAP 1 INH	2 TXS 1 INH	2 AND 2 IMM	3 AND 2 DIR	4 AND 3 EXT	4 AND 3 IX2	5 AND 4 SP2	3 AND 2 IX1	4 AND 3 SP1	2 AND 1 IX
5	5 BRCLR2 3 DIR	4 BCLR2 2 DIR	BCS 2 REL	4 STHX 2 DIR	3 LDHX 3 IMM	4 LDHX 2 DIR	CPHX 3 IMM		4 CPHX 2 DIR	1 TPA 1 INH	2 TSX 1 INH	2 BIT 2 IMM	3 BIT 2 DIR	BIT 3 EXT	4 BIT 3 IX2	5 BIT 4 SP2	3 BIT 2 IX1	4 BIT 3 SP1	2 BIT 1 IX
6	5 BRSET3 3 DIR	4 BSET3 2 DIR	3 BNE 2 REL	4 ROR 2 DIR	1 RORA 1 INH	1 RORX 1 INH	4 ROR 2 IX1	5 ROR 3 SP1	3 ROR 1 IX	2 PULA 1 INH		2 LDA 2 IMM	3 LDA 2 DIR	4 LDA 3 EXT	4 LDA 3 IX2	5 LDA 4 SP2	3 LDA 2 IX1	4 LDA 3 SP1	2 LDA 1 IX
7	5 BRCLR3 3 DIR	4 BCLR3 2 DIR	3 BEQ 2 REL	4 ASR 2 DIR	1 ASRA 1 INH	1 ASRX 1 INH	4 ASR 2 IX1	5 ASR 3 SP1	3 ASR 1 IX	2 PSHA 1 INH	1 TAX 1 INH	AIS 2 IMM	3 STA 2 DIR	4 STA 3 EXT	4 STA 3 IX2	5 STA 4 SP2	3 STA 2 IX1	4 STA 3 SP1	2 STA 1 IX
8	5 BRSET4 3 DIR	4 BSET4 2 DIR	BHCC 2 REL	4 LSL 2 DIR	1 LSLA 1 INH	1 LSLX 1 INH	4 LSL 2 IX1	5 LSL 3 SP1	3 LSL 1 IX	2 PULX 1 INH	1 CLC 1 INH	2 EOR 2 IMM	3 EOR 2 DIR	4 EOR 3 EXT	4 EOR 3 IX2	5 EOR 4 SP2	3 EOR 2 IX1	4 EOR 3 SP1	2 EOR 1 IX
9	5 BRCLR4 3 DIR	4 BCLR4 2 DIR	3 BHCS 2 REL	4 ROL 2 DIR	1 ROLA 1 INH	1 ROLX 1 INH	4 ROL 2 IX1	5 ROL 3 SP1	3 ROL 1 IX	2 PSHX 1 INH	1 SEC 1 INH	ADC 2 IMM	ADC 2 DIR	ADC 3 EXT	4 ADC 3 IX2	5 ADC 4 SP2	ADC 2 IX1	4 ADC 3 SP1	ADC 1 IX
Α	5 BRSET5 3 DIR	4 BSET5 2 DIR	3 BPL 2 REL	4 DEC 2 DIR	1 DECA 1 INH	1 DECX 1 INH	4 DEC 2 IX1	5 DEC 3 SP1	3 DEC 1 IX	2 PULH 1 INH	2 CLI 1 INH	2 ORA 2 IMM	3 ORA 2 DIR	4 ORA 3 EXT	4 ORA 3 IX2	5 ORA 4 SP2	3 ORA 2 IX1	4 ORA 3 SP1	2 ORA 1 IX
В	5 BRCLR5 3 DIR	4 BCLR5 2 DIR	3 BMI 2 REL	5 DBNZ 3 DIR	3 DBNZA 2 INH	3 DBNZX 2 INH	5 DBNZ 3 IX1	6 DBNZ 4 SP1	4 DBNZ 2 IX	2 PSHH 1 INH	2 SEI 1 INH	2 ADD 2 IMM	3 ADD 2 DIR	4 ADD 3 EXT	4 ADD 3 IX2	5 ADD 4 SP2	3 ADD 2 IX1	4 ADD 3 SP1	2 ADD 1 IX
с	5 BRSET6 3 DIR	4 BSET6 2 DIR	3 BMC 2 REL	4 INC 2 DIR	1 INCA 1 INH	1 INCX 1 INH	4 INC 2 IX1	5 INC 3 SP1	3 INC 1 IX	1 CLRH 1 INH	1 RSP 1 INH		2 JMP 2 DIR	3 JMP 3 EXT	4 JMP 3 IX2		3 JMP 2 IX1		2 JMP 1 IX
D	5 BRCLR6 3 DIR	4 BCLR6 2 DIR	3 BMS 2 REL	3 TST 2 DIR	1 TSTA 1 INH	1 TSTX 1 INH	3 TST 2 IX1	4 TST 3 SP1	2 TST 1 IX		1 NOP 1 INH	4 BSR 2 REL	4 JSR 2 DIR	5 JSR 3 EXT	6 JSR 3 IX2		5 JSR 2 IX1		4 JSR 1 IX
E	5 BRSET7 3 DIR	4 BSET7 2 DIR	3 BIL 2 REL		5 MOV 3 DD	4 MOV 2 DIX+	4 MOV 3 IMD		4 MOV 2 IX+D	1 STOP 1 INH	*	2 LDX 2 IMM	3 LDX 2 DIR	4 LDX 3 EXT	4 LDX 3 IX2	5 LDX 4 SP2	3 LDX 2 IX1	4 LDX 3 SP1	2 LDX 1 IX
F	5 BRCLR7 3 DIR	4 BCLR7 2 DIR	3 BIH 2 REL	3 CLR 2 DIR	1 CLRA 1 INH	1 CLRX 1 INH	3 CLR 2 IX1	4 CLR 3 SP1	2 CLR 1 IX	1 WAIT 1 INH	1 TXA 1 INH	AIX 2 IMM	3 STX 2 DIR	STX 3 EXT	4 STX 3 IX2	5 STX 4 SP2	3 STX 2 IX1	4 STX 3 SP1	STX 1 IX

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- INH Inherent IMM Immediate REL Relative IX Indexed, No Offset DIR Direct ÏX1 EXT Extended DD Direct-Direct IX+D Indexed-Direct
 - Indexed, 8-Bit Offset IX2 Indexed, 16-Bit Offset
 - IMD Immediate-Direct DIX+ Direct-Indexed
- SP1 Stack Pointer, 8-Bit Offset SP2 Stack Pointer, 16-Bit Offset IX+ Indexed, No Offset with
- Post Increment IX1+ Indexed, 1-Byte Offset with Post Increment
- Low Byte of Opcode in Hexadecimal

0 High Byte of Opcode in Hexadecimal

0

MSB

LSB

5 Cycles BRSET0 Opcode Mnemonic 3 DIR Number of Bytes / Addressing Mode

- *Pre-byte for stack pointer indexed instructions
- Freescale Semiconductor





10.4 LVI Status Register

The LVI status register (LVISR) indicates if the V_{DD} voltage was detected below the V_{TRIPF} level while LVI resets have been disabled.



Figure 10-2. LVI Status Register (LVISR)

LVIOUT — LVI Output Bit

This read-only flag becomes set when the V_{DD} voltage falls below the V_{TRIPF} trip voltage and is cleared when V_{DD} voltage rises above V_{TRIPR} . The difference in these threshold levels results in a hysteresis that prevents oscillation into and out of reset (see Table 10-1). Reset clears the LVIOUT bit.

V _{DD}	LVIOUT
$V_{DD} > V_{TRIPR}$	0
$V_{DD} < V_{TRIPF}$	1
$V_{TRIPF} < V_{DD} < V_{TRIPR}$	Previous value

Table 10-1. LVIOUT Bit Indication

10.5 LVI Interrupts

The LVI module does not generate interrupt requests.

10.6 Low-Power Modes

The STOP and WAIT instructions put the MCU in low power-consumption standby modes.

10.6.1 Wait Mode

If enabled, the LVI module remains active in wait mode. If enabled to generate resets, the LVI module can generate a reset and bring the MCU out of wait mode.

10.6.2 Stop Mode

When the LVIPWRD bit in the configuration register is cleared and the LVISTOP bit in the configuration register is set, the LVI module remains active in stop mode. If enabled to generate resets, the LVI module can generate a reset and bring the MCU out of stop mode.



Chapter 11 Oscillator Module (OSC)

11.1 Introduction

The oscillator module is used to provide a stable clock source for the microcontroller system and bus. The oscillator module generates two output clocks, BUSCLKX2 and BUSCLKX4. The BUSCLKX4 clock is used by the system integration module (SIM) and the computer operating properly module (COP). The BUSCLKX2 clock is divided by two in the SIM to be used as the bus clock for the microcontroller. Therefore the bus frequency will be one fourth of the BUSCLKX4 frequency.

11.2 Features

The oscillator has these four clock source options available:

- 1. Internal oscillator: An internally generated, fixed frequency clock, trimmable to ±5%. This is the default option out of reset.
- 2. External oscillator: An external clock that can be driven directly into OSC1.
- 3. External RC: A built-in oscillator module (RC oscillator) that requires an external R connection only. The capacitor is internal to the chip.
- 4. External crystal: A built-in oscillator module (XTAL oscillator) that requires an external crystal or ceramic-resonator.

11.3 Functional Description

The oscillator contains these major subsystems:

- Internal oscillator circuit
- Internal or external clock switch control
- External clock circuit
- External crystal circuit
- External RC clock circuit



Oscillator Module (OSC)

11.8.1 Oscillator Status Register

The oscillator status register (OSCSTAT) contains the bits for switching from internal to external clock sources.



Figure 11-4. Oscillator Status Register (OSCSTAT)

ECGON — External Clock Generator On Bit

This read/write bit enables external clock generator, so that the switching process can be initiated. This bit is forced low during reset. This bit is ignored in monitor mode with the internal oscillator bypassed, PTM or CTM mode.

1 = External clock generator enabled

0 = External clock generator disabled

ECGST — External Clock Status Bit

This read-only bit indicates whether or not an external clock source is engaged to drive the system clock.

1 = An external clock source engaged

0 = An external clock source disengaged

11.8.2 Oscillator Trim Register (OSCTRIM)



Figure 11-5. Oscillator Trim Register (OSCTRIM)

TRIM7–TRIM0 — Internal Oscillator Trim Factor Bits

These read/write bits change the size of the internal capacitor used by the internal oscillator. By measuring the period of the internal clock and adjusting this factor accordingly, the frequency of the internal clock can be fine tuned. Increasing (decreasing) this factor by one increases (decreases) the period by approximately 0.2% of the untrimmed period (the period for TRIM = \$80). The trimmed frequency is guaranteed not to vary by more than $\pm 5\%$ over the full specified range of temperature and voltage. The reset value is \$80, which sets the frequency to 12.8 MHz (3.2 MHz bus speed) $\pm 25\%$.

Applications using the internal oscillator should copy the internal oscillator trim value at location \$FFC0 or \$FFC1 into this register to trim the clock source.



Input/Output Ports (PORTS)

12.2.1 Port A Data Register

The port A data register (PTA) contains a data latch for each of the six port A pins.



Figure 12-1. Port A Data Register (PTA)

PTA[5:0] — Port A Data Bits

These read/write bits are software programmable. Data direction of each port A pin is under the control of the corresponding bit in data direction register A. Reset has no effect on port A data.

AWUL — Auto Wakeup Latch Data Bit

This is a read-only bit which has the value of the auto wakeup interrupt request latch. The wakeup request signal is generated internally (see Chapter 4 Auto Wakeup Module (AWU)). There is no PTA6 port nor any of the associated bits such as PTA6 data register, pullup enable or direction.

KBI[5:0] — Port A Keyboard Interrupts

The keyboard interrupt enable bits, KBIE5–KBIE0, in the keyboard interrupt control enable register (KBIER) enable the port A pins as external interrupt pins (see Chapter 9 Keyboard Interrupt Module (KBI)).

12.2.2 Data Direction Register A

Data direction register A (DDRA) determines whether each port A pin is an input or an output. Writing a 1 to a DDRA bit enables the output buffer for the corresponding port A pin; a 0 disables the output buffer.



Figure 12-2. Data Direction Register A (DDRA)

DDRA[5:0] — Data Direction Register A Bits

These read/write bits control port A data direction. Reset clears DDRA[5:0], configuring all port A pins as inputs.

1 = Corresponding port A pin configured as output

0 = Corresponding port A pin configured as input

NOTE

Avoid glitches on port A pins by writing to the port A data register before changing data direction register A bits from 0 to 1.

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14.4 Functional Description

Figure 14-2 shows the structure of the TIM. The central component of the TIM is the 16-bit TIM counter that can operate as a free-running counter or a modulo up-counter. The TIM counter provides the timing reference for the input capture and output compare functions. The TIM counter modulo registers, TMODH:TMODL, control the modulo value of the TIM counter. Software can read the TIM counter value at any time without affecting the counting sequence.

The two TIM channels are programmable independently as input capture or output compare channels.



Figure 14-2. TIM Block Diagram



Timer Interface Module (TIM)

14.4.4.1 Unbuffered PWM Signal Generation

Any output compare channel can generate unbuffered PWM pulses as described in 14.4.4 Pulse Width Modulation (PWM). The pulses are unbuffered because changing the pulse width requires writing the new pulse width value over the old value currently in the TIM channel registers.

An unsynchronized write to the TIM channel registers to change a pulse width value could cause incorrect operation for up to two PWM periods. For example, writing a new value before the counter reaches the old value but after the counter reaches the new value prevents any compare during that PWM period. Also, using a TIM overflow interrupt routine to write a new, smaller pulse width value may cause the compare to be missed. The TIM may pass the new value before it is written.

Use the following methods to synchronize unbuffered changes in the PWM pulse width on channel x:

- When changing to a shorter pulse width, enable channel x output compare interrupts and write the new value in the output compare interrupt routine. The output compare interrupt occurs at the end of the current pulse. The interrupt routine has until the end of the PWM period to write the new value.
- When changing to a longer pulse width, enable TIM overflow interrupts and write the new value in the TIM overflow interrupt routine. The TIM overflow interrupt occurs at the end of the current PWM period. Writing a larger value in an output compare interrupt routine (at the end of the current pulse) could cause two output compares to occur in the same PWM period.

NOTE

In PWM signal generation, do not program the PWM channel to toggle on output compare. Toggling on output compare prevents reliable 0% duty cycle generation and removes the ability of the channel to self-correct in the event of software error or noise. Toggling on output compare also can cause incorrect PWM signal generation when changing the PWM pulse width to a new, much larger value.

14.4.4.2 Buffered PWM Signal Generation

Channels 0 and 1 can be linked to form a buffered PWM channel whose output appears on the TCH0 pin. The TIM channel registers of the linked pair alternately control the pulse width of the output.

Setting the MS0B bit in TIM channel 0 status and control register (TSC0) links channel 0 and channel 1. The TIM channel 0 registers initially control the pulse width on the TCH0 pin. Writing to the TIM channel 1 registers enables the TIM channel 1 registers to synchronously control the pulse width at the beginning of the next PWM period. At each subsequent overflow, the TIM channel registers (0 or 1) that control the pulse width are the ones written to last. TSC0 controls and monitors the buffered PWM function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

NOTE

In buffered PWM signal generation, do not write new pulse width values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered PWM signals.



If monitor mode was entered with V_{TST} on \overline{IRQ} , then the COP is disabled as long as V_{TST} is applied to IRQ.

15.3.1.2 Forced Monitor Mode

If entering monitor mode without high voltage on IRQ, then startup port pin requirements and conditions, (PTA1/PTA4) are not in effect. This is to reduce circuit requirements when performing in-circuit programming.

NOTE

If the reset vector is blank and monitor mode is entered, the chip will see an additional reset cycle after the initial power-on reset (POR). Once the reset vector has been programmed, the traditional method of applying a voltage, V_{TST} , to \overline{IRQ} must be used to enter monitor mode.

If monitor mode was entered as a result of the reset vector being blank, the COP is always disabled regardless of the state of IRQ.

If the voltage applied to the \overline{IRQ} is less than V_{TST} , the MCU will come out of reset in user mode. Internal circuitry monitors the reset vector fetches and will assert an internal reset if it detects that the reset vectors are erased (\$FF). When the MCU comes out of reset, it is forced into monitor mode without requiring high voltage on the \overline{IRQ} pin. Once out of reset, the monitor code is initially executing with the internal clock at its default frequency.

If IRQ is held high, all pins will default to regular input port functions except for PTA0 and PTA5 which will operate as a serial communication port and OSC1 input respectively (refer to Figure 15-10). That will allow the clock to be driven from an external source through OSC1 pin.

If IRQ is held low, all pins will default to regular input port function except for PTA0 which will operate as serial communication port. Refer to Figure 15-11.

Regardless of the state of the \overline{IRQ} pin, it will not function as a port input pin in monitor mode. Bit 2 of the Port A data register will always read 0. The BIH and BIL instructions will behave as if the \overline{IRQ} pin is enabled, regardless of the settings in the configuration register. See Chapter 5 Configuration Register (CONFIG).

The COP module is disabled in forced monitor mode. Any reset other than a power-on reset (POR) will automatically force the MCU to come back to the forced monitor mode.

15.3.1.3 Monitor Vectors

In monitor mode, the MCU uses different vectors for reset, SWI (software interrupt), and break interrupt than those for user mode. The alternate vectors are in the \$FE page instead of the \$FF page and allow code execution from the internal monitor firmware instead of user code.

NOTE

Exiting monitor mode after it has been initiated by having a blank reset vector requires a power-on reset (POR). Pulling RST (when RST pin available) low will not exit monitor mode in this situation.

Table 15-2 summarizes the differences between user mode and monitor mode regarding vectors.



16.14 Analog-to-Digital Converter Characteristics

Characteristic	Symbol	Min	Max	Unit	Comments		
Supply voltage	V _{DDAD}	2.7 (V _{DD} min)	5.5 (V _{DD} max)	V	_		
Input voltages	V _{ADIN}	V _{SS}	V _{DD}	V	—		
Resolution (1 LSB)	RES	10.5	21.5	mV	—		
Absolute accuracy (Total unadjusted error)	E _{TUE}	_	± 1.5	LSB	Includes quantization		
ADC internal clock	f _{ADIC}	0.5	1.048	MHz	t _{ADIC} = 1/f _{ADIC} , tested only at 1 MHz		
Conversion range	V _{AIN}	V _{SS}	V _{DD}	V	—		
Power-up time	t _{ADPU}	16	—	t _{ADIC} cycles	$t_{ADIC} = 1/f_{ADIC}$		
Conversion time	t _{ADC}	16	17	t _{ADIC} cycles	$t_{ADIC} = 1/f_{ADIC}$		
Sample time ⁽¹⁾	t _{ADS}	5	—	t _{ADIC} cycles	$t_{ADIC} = 1/f_{ADIC}$		
Zero input reading ⁽²⁾	Z _{ADI}	00	01	Hex	$V_{IN} = V_{SS}$		
Full-scale reading ⁽³⁾	F _{ADI}	FE	FF	Hex	$V_{IN} = V_{DD}$		
Input capacitance	C _{ADI}	—	8	pF	Not tested		
Input leakage ⁽³⁾	IIL	—	± 1	μA	—		
ADC supply current $V_{DD} = 3 V$ $V_{DD} = 5 V$	I _{ADAD}	Туріса Туріса	l = 0.45 l = 0.65	mA mA	Enabled Enabled		

1. Source impedances greater than 10 kΩ adversely affect internal RC charging time during input sampling.

2. Zero-input/full-scale reading requires sufficient decoupling measures for accurate conversions.

3. The external system error caused by input leakage current is approximately equal to the product of R source and input current.

